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Estimation of charge carrier mobility in polymer thin-film structures

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Abstract

© Published under licence by IOP Publishing Ltd. In this article, the polymer polydiphenylenphthalide. The estimates of the mobility of charge carriers for FDP films of different thicknesses by the CELIV method are carried out. During the measurements it was concluded that the mobility value does not depend on the thickness of the polymer film within 100-800 nm.

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